

Photocouplers Infrared LED & Photo Triac

# TLP267J

#### 1. Applications

- · Triac Drivers
- · Programmable Logic Controllers (PLCs)
- · AC-Output Modules
- · Solid-State Relays

#### 2. General

The TLP267J consists of a non zero crossing photo triac, optically coupled to an infrared LED. The TLP267J is housed in the SO6 package and guarantees a creepage distance of 5.0 mm (min), a clearance of 5.0 mm (min) and internalisolation thickness of 0.4 mm (min). Therefore, the TLP267J meets the reinforced insulation class requirements of international safety standards.

#### 3. Features

(1) Peak off-state voltage: 600 V (min)

(2) Non zero crossing functionary (NZC)

(3) Trigger LED current: 3 mA (max)

(4) On-state current: 70 mA (max)

(5) Isolation voltage: 3750 Vrms (min)

(6) Safety standards

UL-recognized: UL 1577, File No.E67349

cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN 60747-5-5, EN 62368-1 (Note 1) CQC-approved: GB4943.1, GB8898 Thailand Factory



仅适用干海拔 2000m 以下地区安全使用

Note 1: When a VDE approved type is needed, please designate the Option (V4).

#### Table Trigger LED Current (Note) (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Rank	I <sub>FT</sub> Rank Marking	Test Condition	Trigger LED Current I <sub>FT</sub> (min)	Trigger LED Current I <sub>FT</sub> (max)	Unit
None	3	V <sub>T</sub> = 6 V	_	3	mA
(IFT2)	2	V <sub>T</sub> = 6 V	_	2	

Note: Specify both the part number and a rank in this format when ordering.

Example: TLP267J (IFT2)

For safety standard certification, however, specify the part number alone.

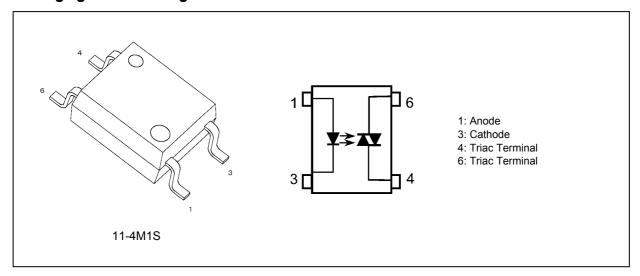
Example: TLP267J

Start of commercial production

2013-10



### 4. Packaging and Pin Assignment



#### 5. Mechanical Parameters

Characteristics	2.54-mm pitch	Unit
Creepage distances	5.0 (min)	mm
Clearance distances	5.0 (min)	
Internal isolation thickness	0.4 (min)	

### 6. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example: TLP267J(TPL,E

Part number: TLP267J
Tape type: TPL (Note 1)

[[G]]/RoHS COMPATIBLE: E (Note 2)

Note 1: At the part of tape type, below options are used.

TPL, TPR

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



### 7. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I <sub>F</sub>		30	mA
	Input forward current derating	(T <sub>a</sub> ≥ 25 °C)	$\Delta I_F/\Delta T_a$		-0.3	mA/°C
	Input forward current (pulsed)		I <sub>FP</sub>	(Note 1)	1	Α
	Input reverse voltage		$V_R$		5	V
	Input power dissipation		$P_D$		50	mW
	Input power dissipation derating	(T <sub>a</sub> ≥ 25 °C)	$\Delta P_D/\Delta T_a$		-0.5	mW/°C
	Junction temperature		Tj		125	°C
Detector	Off-state output terminal voltage		$V_{DRM}$		600	V
	R.M.S. on-state current	(T <sub>a</sub> = 25 °C)	I <sub>T(RMS)</sub>		70	mA
	R.M.S. on-state current	(T <sub>a</sub> = 70 °C)	I <sub>T(RMS)</sub>		40	mA
	R.M.S. on-state current derating	(T <sub>a</sub> ≥ 25 °C)	$\Delta I_{T(RMS)}/\Delta T_a$		-0.67	mA/°C
	ON-state current (pulsed)		I <sub>ONP</sub>	(Note 2)	2	Α
	Peak non-repetitive surge current		I <sub>TSM</sub>	(Note 3)	1.2	Α
	Output power dissipation		Po		200	mW
	Output power dissipation derating	$(T_a \ge 25  ^{\circ}C)$	$\Delta P_O/\Delta T_a$		-2	mW/°C
	Junction temperature		Tj		125	°C
Common	Operating temperature		T <sub>opr</sub>		-40 to 100	°C
	Storage temperature		T <sub>stg</sub>		-55 to 125	
	Lead soldering temperature	(10 s)	T <sub>sol</sub>		260	°C
	Isolation voltage	AC, 60 s, R.H. ≤ 60 %	BV <sub>S</sub>	(Note 4)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Pulse width (PW)  $\leq$  100  $\mu$ s, 100 pps
- Note 2: Pulse width (PW)  $\leq$  100  $\mu s,~120~pps$
- Note 3: Pulse width (PW)  $\leq$  10 ms
- Note 4: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

# 8. Recommended Operating Conditions (Note)

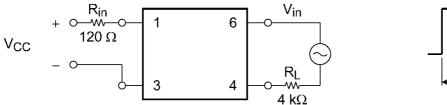
Characteristics	Symbol	Note	Min	Тур.	Max	Unit
AC mains voltage	V <sub>AC</sub>		_	_	240	V
Input forward current	I <sub>F</sub>		4.5	6	7.5	mA
ON-state current (pulsed)	I <sub>ONP</sub>		_	_	1	Α
Operating temperature	T <sub>opr</sub>		-25	_	85	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.



# 9. Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V <sub>F</sub>		I <sub>F</sub> = 10 mA	1.0	1.27	1.4	V
	Input reverse current	I <sub>R</sub>		V <sub>R</sub> = 5 V	_		10	μΑ
	Input capacitance	Ct		V = 0 V, f = 1 MHz	_	30	_	pF
Detector	Peak off-state current	I <sub>DRM</sub>		V <sub>DRM</sub> = 600 V		10	1000	nA
	Peak on-state voltage	V <sub>TM</sub>		I <sub>TM</sub> = 70 mA		1.7	2.8	V
	Holding current	Η			_	0.2	_	mA
	Critical rate of rise of off-state voltage	dv/dt		V <sub>in</sub> = 240 V, T <sub>a</sub> = 85 °C See Fig. 9.1		500		V/μs
	Critical rate of rise of commutating voltage (dv/dt)	dv/dt(c)		V <sub>in</sub> = 60 Vrms, I <sub>T</sub> = 15 mA See Fig. 9.1	_	0.2	_	



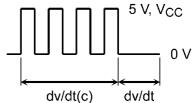


Fig. 9.1 dv/dt Test Circuit and Waveform

### 10. Coupled Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Trigger LED current	I <sub>FT</sub>		V <sub>T</sub> = 6 V	_	_	3	mA
Turn-on time	t <sub>on</sub>		$V_D$ = 6 $\rightarrow$ 4 V, $R_L$ = 100 $\Omega$ , $I_F$ = Rated $I_{FT} \times 1.5$	_	_	100	μS

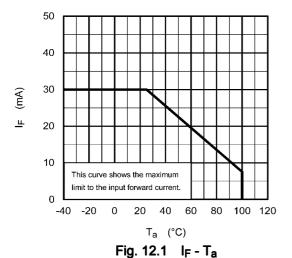
# 11. Isolation Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	V <sub>S</sub> = 0 V, f = 1 MHz	_	0.8		pF
Isolation resistance	R <sub>S</sub>	(Note 1)	$V_S = 500 \text{ V}, \text{ R.H.} \le 60\%$	1012	1014	_	Ω
Isolation voltage	BV <sub>S</sub>	(Note 1)	AC, 60 s	3750	_	_	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.



#### 12. Characteristics Curves (Note)



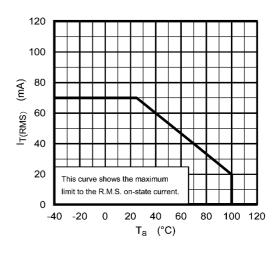
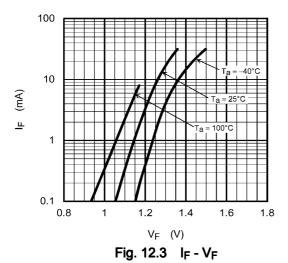
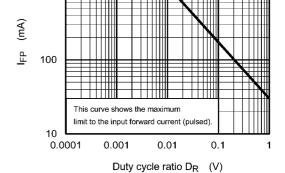


Fig. 12.2 I<sub>T(RMS)</sub> - T<sub>a</sub>

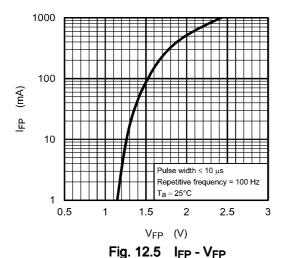
Pulse width  $\leq 100 \ \mu s$  $T_a = 25$ °C





1000

Fig. 12.4 I<sub>FP</sub> - D<sub>R</sub>



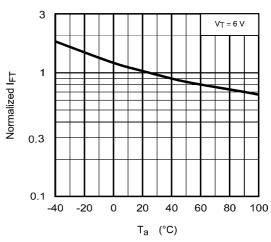


Fig. 12.6 Normalized I<sub>FT</sub> - T<sub>a</sub>



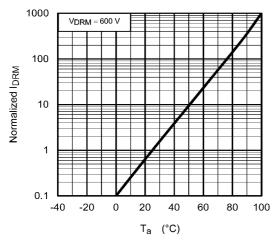


Fig. 12.7 Normalized IDRM - Ta

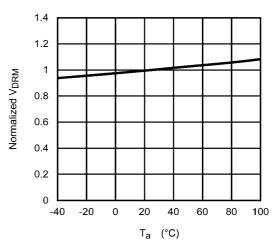


Fig. 12.8 Normalized V<sub>DRM</sub> - T<sub>a</sub>

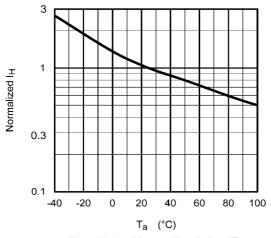


Fig. 12.9 Normalized I<sub>H</sub> - T<sub>a</sub>

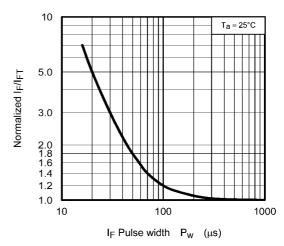


Fig. 12.10 Normalized I<sub>F</sub>/I<sub>FT</sub> - I<sub>F</sub>\_P<sub>W</sub>

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



#### 13. Soldering and Storage

#### 13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

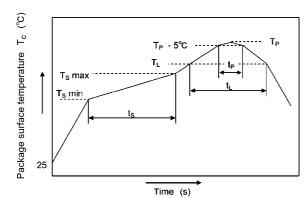
· When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )			3	°C/s
Liquidus temperature	TL	217		°C
Time above T <sub>L</sub>	t∟	60	150	s
Peak temperature	T <sub>P</sub>		260	°C
Time during which $T_c$ is between $(T_P - 5)$ and $T_P$	t <sub>P</sub>		30	s
Ramp-down rate (T <sub>P</sub> to T <sub>L</sub> )			6	°C/s

Fig. 13.1.1 An example of a temperature profile when lead(Pb)-free solder is used

· When using soldering flow

Preheat the device at a temperature of 150  $^{\circ}\text{C}$  (package surface temperature) for 60 to 120 seconds.

Mounting condition of 260  $^{\circ}$ C within 10 seconds is recommended.

Flow soldering must be performed once.

· When using soldering Iron

Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

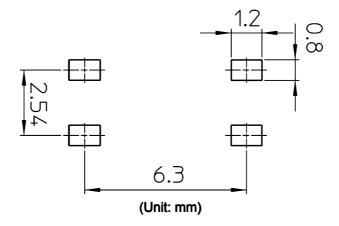
Heating by soldering iron must be done only once per lead.

#### 13.2. Precautions for General Storage

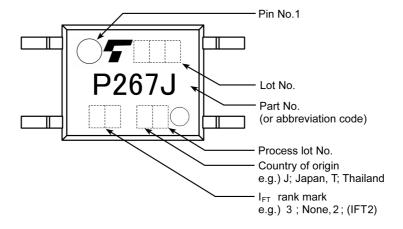
- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45% to 75%, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- · When restoring devices after removal from their packing, use anti-static containers.
- · Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.



# 14. Land Pattern Dimensions (for reference only)



### 15. Marking (Note)



Note: A different marking is used for photocouplers that have been qualified according to option (V4) of EN 60747. See Fig.16.3 and Fig.16.4.



### 16. EN 60747-5-5 Option (V4) Specification

• Part number: TLP267J (Note)

• The following part naming conventions are used for the devices that have been qualified according to option (V4) of EN 60747.

Example: TLP267J(V4-TPL,E

V4: EN 60747 option TPL: Tape type

E: [[G]]/RoHS COMPATIBLE (Note 1)

Note: Use TOSHIBA standard type number for safety standard application.

e.g., TLP267J(V4-TPL,E  $\rightarrow$  TLP267J

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

	Description	Symbol	Rating	Unit
Application classification				
for rated mains volta		I-IV I-III	_	
Climatic classification			55 / 100 / 21	_
Pollution degree			2	_
Maximum operating insu	lation voltage	VIORM	707	Vpeak
Input to output test voltage $V_{pr} = 1.6 \times V_{IORM}$ , the total voltage $t_p = 10$ s, partial disconnections $t_p = 10$	ype and sample test	V <sub>pr</sub>	1131	Vpeak
Input to output test voltage $V_{pr}$ = 1.875 × $V_{IORM}$ $t_p$ = 1 s, partial disch	1, 100 % production test	V <sub>pr</sub>	1325	Vpeak
Highest permissible over (transient overvoltag	9	V <sub>TR</sub>	6000	Vpeak
	· · · · · · · · · · · · · · · · · · ·	I <sub>si</sub> P <sub>so</sub> T <sub>s</sub>	250 400 150	mA mW °C
Insulation resistance	$V_{IO}$ = 500 V, $T_a$ = 25 °C $V_{IO}$ = 500 V, $T_a$ = 100 °C $V_{IO}$ = 500 V, $T_a$ = $T_s$	R <sub>si</sub>	≥ 10 <sup>12</sup> ≥ 10 <sup>11</sup> ≥ 10 <sup>9</sup>	Ω

Fig. 16.1 EN 60747 Insulation Characteristics



Minimum creepage distance	Cr	5.0 mm
Minimum clearance	Cl	5.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	CTI	175

Fig. 16.2 Insulation Related Specifications (Note)

Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e. g., at a standard distance between soldering eye centers of 3.5 mm). If this is not permissible, the user shall take suitable measures.

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 16.3 Marking on packing

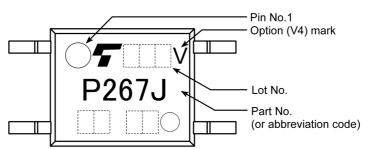
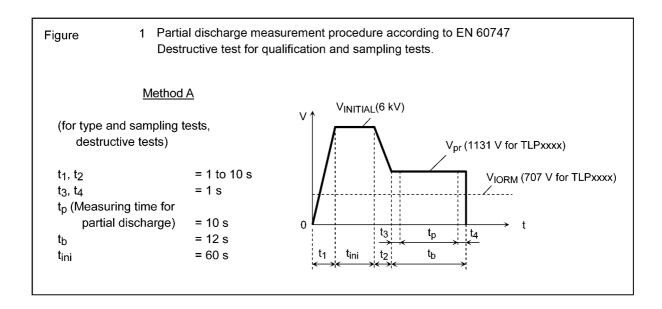
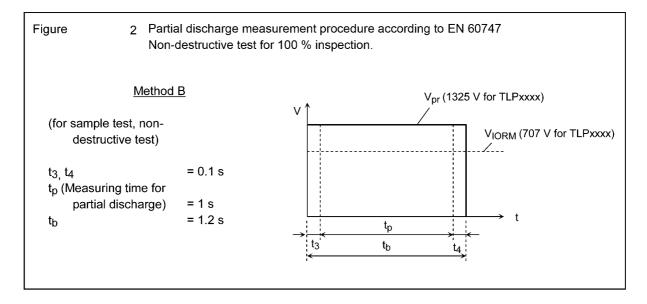


Fig. 16.4 Marking Example (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (V4) of EN 60747.







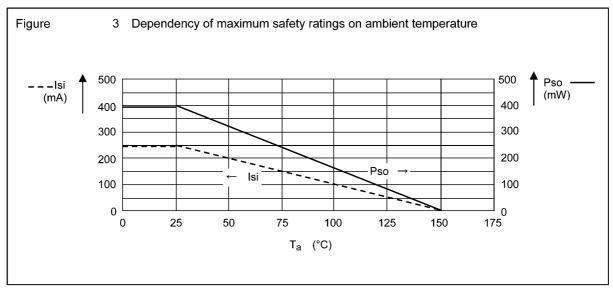
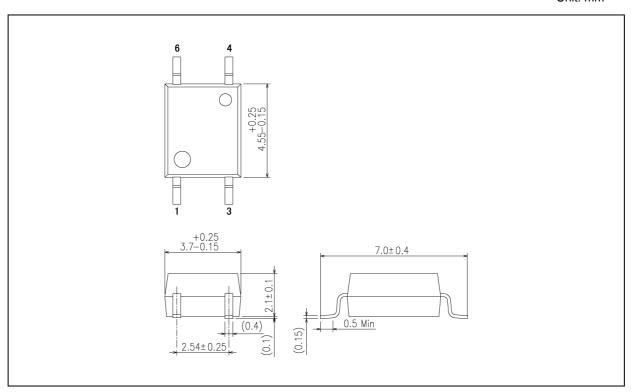


Fig. 16.5 Measurement Procedure



# **Package Dimensions**

Unit: mm



Weight: 0.08 g (typ.)

	Package Name(s)
TOSHIBA: 11-4M1S	



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2020-02-17

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